

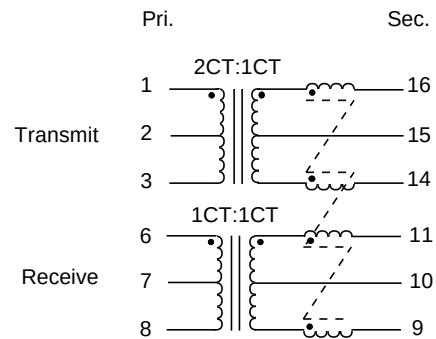


- Robust design allows for toughest soldering processes •
- Provided with superior common mode attenuation •
- Complies with or exceeds IEEE 802.3, 10 Base-T Requirements •

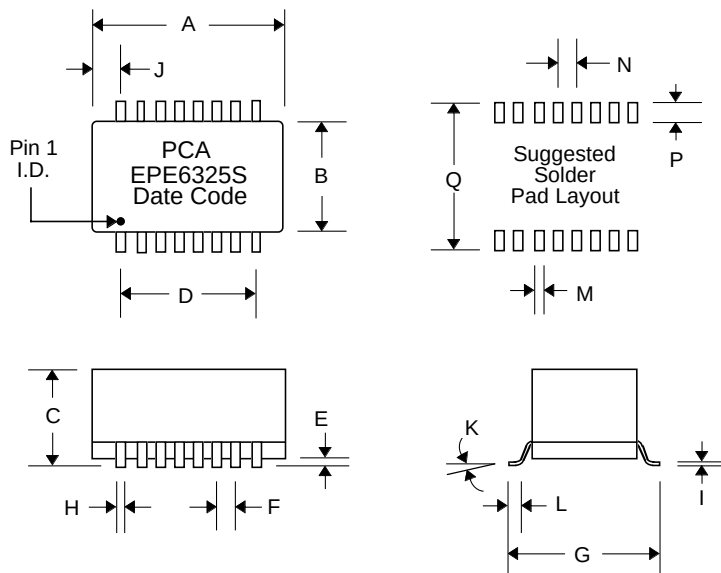
Electrical Parameters @ 25° C

Secondary Inductance (μ H Min.)		Interwinding Capacitance (pF Max.)	CMRR (dB Min.)				Return Loss (dB Min.)	Hipot (Vrms)	Primary DCR (Ω Max.)	
@ 100 KHz, 0.1 Vrms		@ 100 KHz, 0.1 Vrms	30-100 MHz		200 MHz		5MHz-10MHz			
Xmit	Rcv		Xmit	Rcv	Xmit	Rcv			Xmit	Rcv
200	200	17	-30	-30	-20	-20	-15	1500	1.0	0.50

Schematic



Package



Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	.480	.500		12.19	12.70	
B	.260	.280		6.60	7.11	
C	.210	.230		5.33	5.84	
D	.350	Typ.		8.89	Typ.	
E	.010	.015		.254	.381	
F	.050	Typ.		1.27	Typ.	
G	.370	.390		9.40	9.91	
H	.016	.022		.406	.559	
I	.010	Typ.		.254	Typ.	
J	.070	Typ.		1.78	Typ.	
K	0°	8°		0°	8°	
L	.025	.045		.635	1.14	
M			.030			.762
N			.050			1.27
P			.055			1.40
Q			.410			10.41